

ING.

4. LEAD TO LEAD CAPACITANCE SHALL NOT EXCEED 8 P.F. AT 1 MHz.

5. LEAD RESISTANCE SHALL BE 0.2Ω MAX.

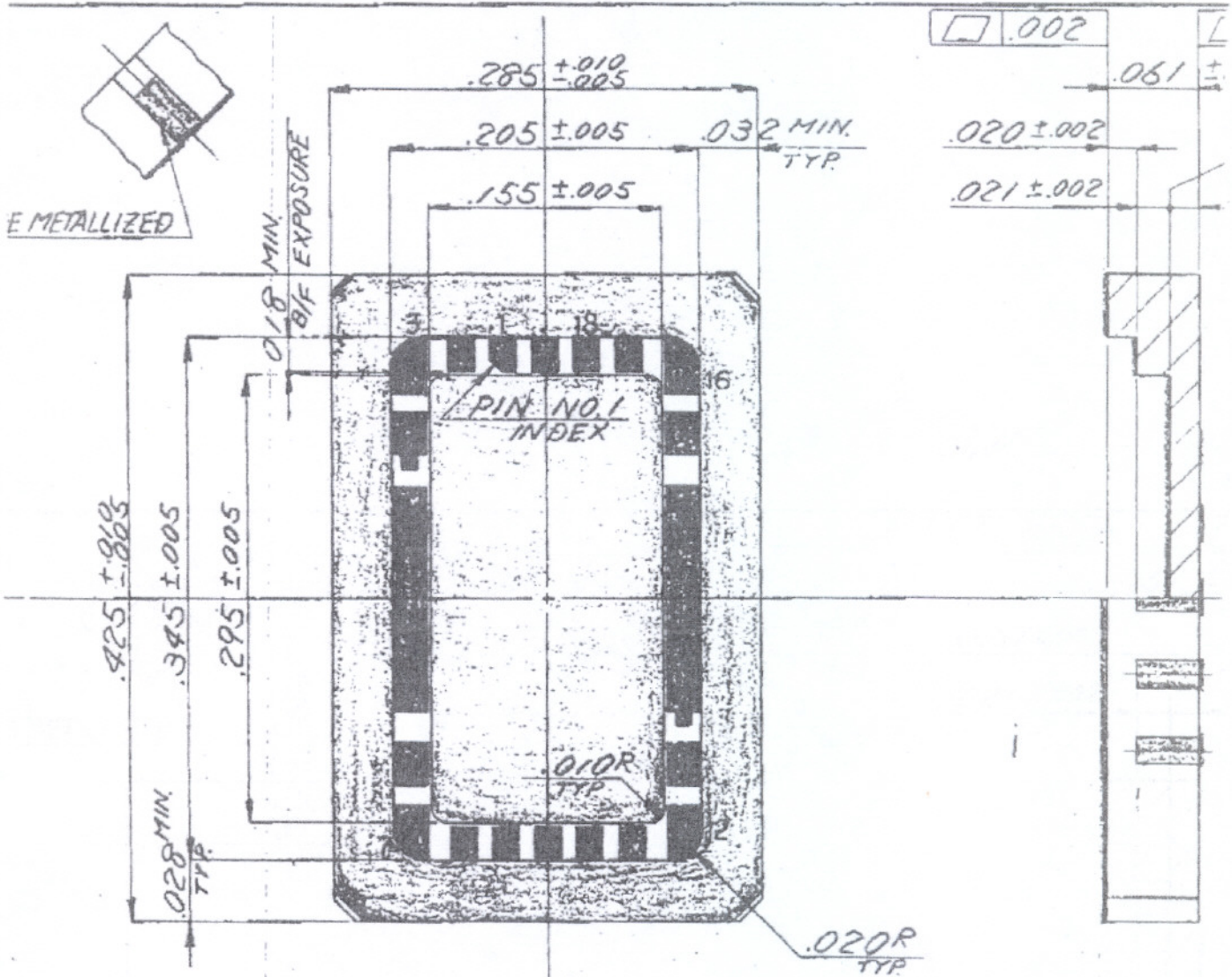
WPS

6. DIE ATTACH PAD TO BE CONNECTED PIN NO 18

S = 0
D = 18

000-18CZ

NAME (000-18CZ)		TOLERANCES: UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED
18LCC	295x155 CAV.		S. Yamamura	S. Tabata
SCALE	MATERIAL	±.005	APPROVED	DATE
10/1	KYOCERA A-440		S. Tabata	1.26.87
APPROVED	KYOTO CERAMIC CO., LTD.	KYOTO JAPAN	DWG. # PB-C87037	1/2

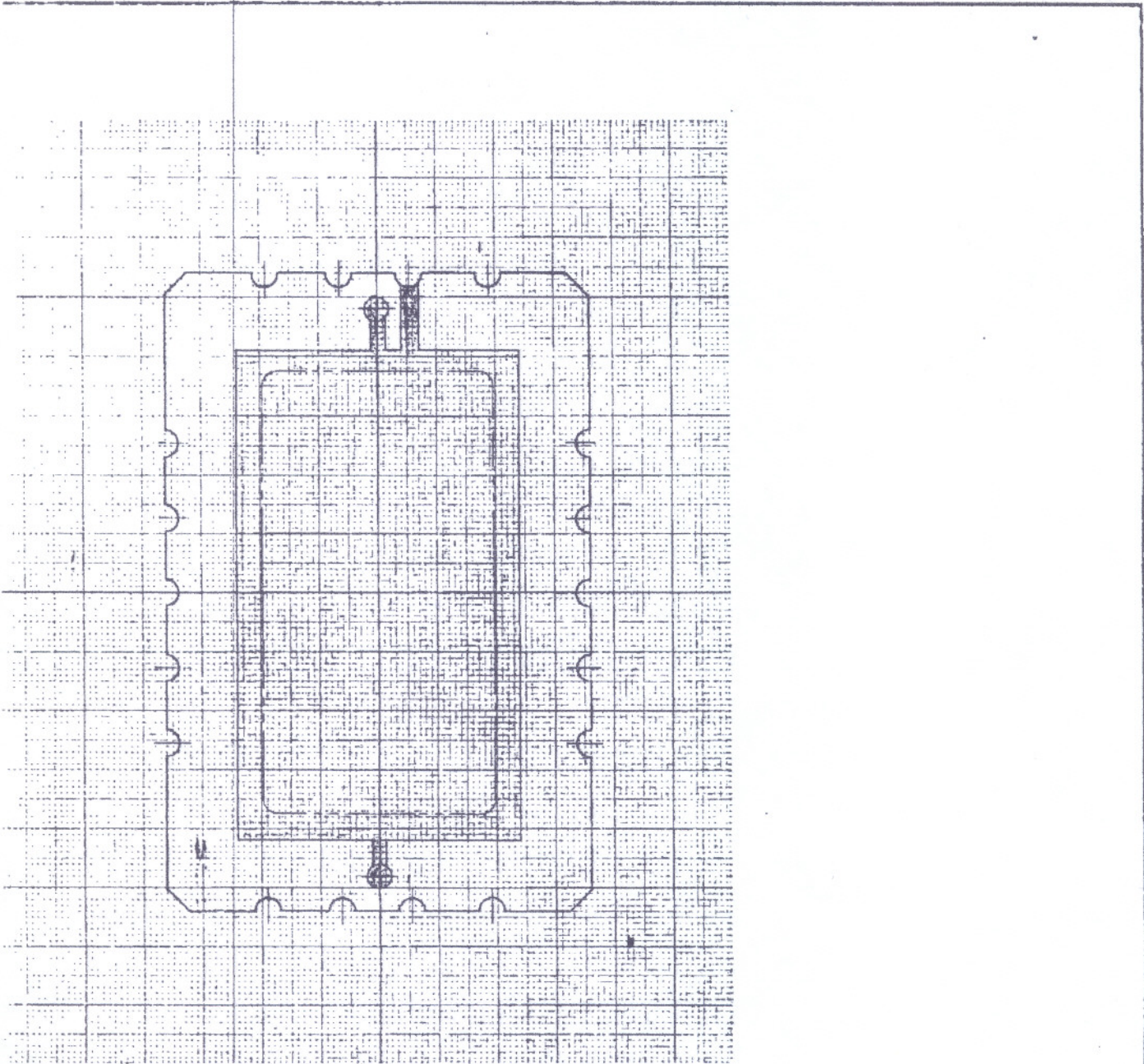


$.002$	L
$.061 \pm$	
$.020 \pm .002$	
$.021 \pm .002$	

NOTE

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCHES MIN. THICKNESS OVER NICKEL PLATING. UNLESS OTHERWISE SPECIFIED IN PURCHASE ORDER. 4.
2. FLATNESS PERTAINS TO METALLIZED PADS ONLY. 5.
3. LEAD TO LEAD LEAKAGE MUST NOT EXCEED 10 NANO AMPS AT 100 V D.C. 6.

					NAME
					18LCC
					SCALE
					10/1
CHANGE	DATE	DRAWN	CHECKED	APPROVED	KY



DIE ATTACH PATTERN

NAME 18LCC		TOLERANCES: UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED
SCALE 10/1	MATERIAL		APPROVED	DATE
			S. Takayama	1.26.87